Abstract

PACKAGED MICROELECTRONIC DEVICES AND METHODS OF FORMING SAME

Microelectronic devices in accordance with aspects of the invention may include a die, a plurality of lead fingers and an encapsulant which may bond the lead fingers and the die. In one method of the invention, a lead frame and a die are releasably attached to a support, an encapsulant is applied, and the support can be removed to expose back contacts of the lead fingers and a back surface of the die. One microelectronic device assembly of the invention includes a die having an exposed back die surface; a plurality of electrical leads, each of which includes front and back electrical contacts; bonding wires electrically coupling the die to the electrical leads; and an encapsulant bonded to the die and the electrical leads. The rear electrical contacts of the electrical leads may be exposed adjacent a back surface of the encapsulant in a staggered array.

Figure 1